www.ti.com

SCAS738D-DECEMBER 2003-REVISED JUNE 2008

HEX BUFFER/DRIVER WITH OPEN-DRAIN OUTPUTS

FEATURES

- Operates From 1.65 V to 5 V
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5 V
- Max t_{pd} of 3.6 ns at 5 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (-55°C/125°C), Industrial (-40°C/85°C) Temperature Ranges⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability
- (1) Custom Temperature Ranges Available

(TOP VIEW) 14 🛮 V_{CC} 13 **6**A 1Y **[** 2A [3 12 ∏ 6Y **∏** 5A 3A**∏**5 10 **∏** 5Y **3Y**[9 1 4A 6 ∏ 4Y GND 8

PW PACKAGE

DESCRIPTION/ORDERING INFORMATION

This hex buffer/driver is designed for 1.65-V to 5.5-V V_{CC} operation.

The outputs of the SN74LVC07A device are open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 24 mA.

Inputs can be driven from 1.8-V, 2.5-V, 3.3-V (LVTTL), or 5-V (CMOS) devices. This feature allows the use of this device as a translator in a mixed-system environment.

ORDERING INFORMATION

T _A	PAC	KAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – PW	Reel of 2000	SN74LVC07AIPWREP	C07AEP
-55°C to 125°C	TSSOP - PW	Reel of 2000	SN74LVC07AMPWREP	C07AMEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each buffer/driver)

INPUT A	OUTPUT Y
Н	Н
L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



LOGIC DIAGRAM, EACH BUFFER/DRIVER (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIM	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Output voltage range		-0.5	6.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or	GND		±100	mA
θ_{JA}	Package thermal impedance (3)			113	°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	5.5	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
\/	High level input veltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
V_{IH}	High-level input voltage	V _{CC} =2.7 V to 3.6 V	2	2	
	High-level input voltage Low-level input voltage Input voltage Output voltage Low-level output current	V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	
V	/ Low level input veltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
V_{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
	Input voltage	V _{CC} = 4.5 V to 5.5 V		0.3 × V _{CC}	<u> </u>
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	5.5	V
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		12	
I_{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
		V _{CC} = 4.5 V		24	
_	On a series of the control of the series and the se	SN74LVC07AIPWREP	-40	85	۰.
T_A	Operating free-air temperature	SN74LVC07AMPWREP	-55	125	°C

All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

www.ti.com

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾ MAX	UNIT		
	I _{OL} = 100 μA	1.65 V to 5.5 V	0.2			
	I _{OL} = 4 mA	1.65 V	0.45			
V _{OL}	1 42 m/s	2.3 V	0.7	V		
	I _{OL} = 12 mA	2.7 V	2.7 V 0.4			
	I _{OL} = 24 mA	3 V	0.55			
I _I	V _I = 5.5 V or GND	3.6 V	±5	μΑ		
I _{cc}	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10	μΑ		
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V	500	μΑ		
Cı	$V_I = V_{CC}$ or GND	3.3 V	5	pF		

⁽¹⁾ All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.2		V _{CC} =	2.7 V	V _{CC} = 3 ±0.3			= 5 V .5 V	UNIT
		(INFOI) (OUTFOI)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Υ	1	6.6	1	4.4		4.3	1	4.6	1	3.6	ns

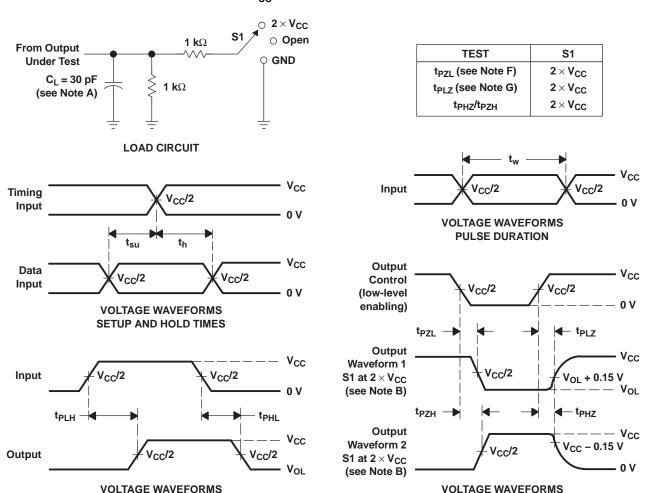
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT
	TANAMETER	CONDITIONS	TYP	TYP	TYP	TYP TYP	
C_{pd}	Power dissipation capacitance	f = 10 MHz	1.8	2	2.5	3.78	pF



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

PROPAGATION DELAY TIMES

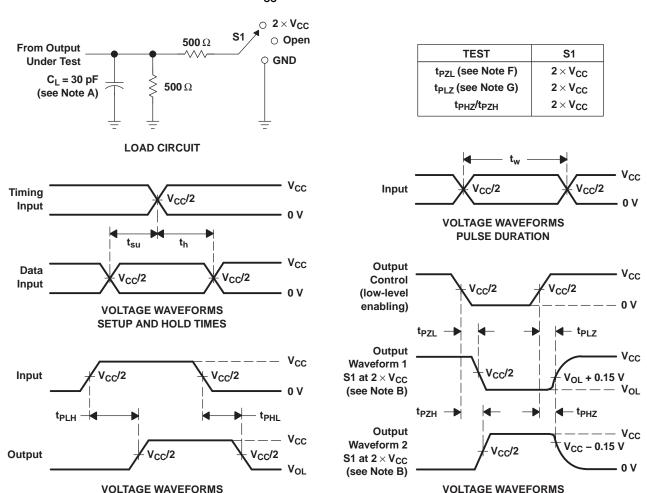
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd} .
- F. t_{PZL} is measured at $V_{CC}/2$.
- G. t_{PLZ} is measured at V_{OL} + 0.15 V.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

ENABLE AND DISABLE TIMES



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

PROPAGATION DELAY TIMES

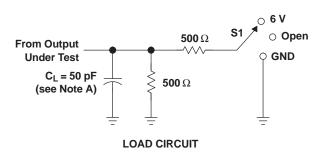
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd} .
- F. t_{PZL} is measured at $V_{CC}/2$.
- G. t_{PLZ} is measured at V_{OL} + 0.15 V.
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

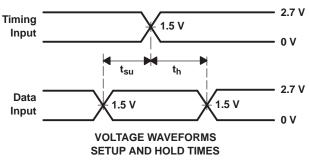
ENABLE AND DISABLE TIMES

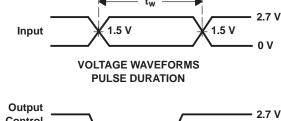


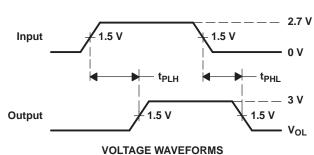
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7 \text{ V}$ AND 3.3 V $\pm 0.3 \text{ V}$



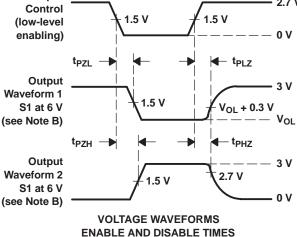
TEST	S1
t _{PZL} (see Note F)	6 V
t _{PLZ} (see Note G)	6 V
t _{PHZ} /t _{PZH}	6 V







PROPAGATION DELAY TIMES



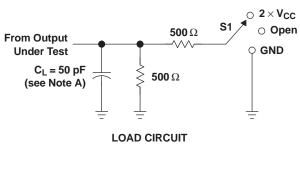
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd} .
- F. t_{PZL} is measured at 1.5 V.
- G. t_{PLZ} is measured at $V_{OL} + 0.3 V$.
- H. All parameters and waveforms are not applicable to all devices.

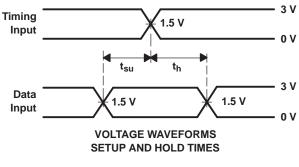
Figure 3. Load Circuit and Voltage Waveforms

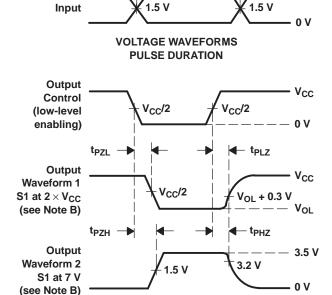


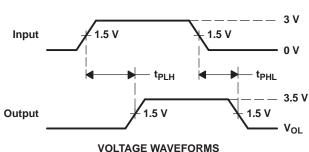
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$



TEST	S1
t _{PZL} (see Note F)	2×V _{CC}
t _{PLZ} (see Note G)	2×V _{CC}
t _{PHZ} /t _{PZH}	7 V







PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd}
- F. t_{PZL} is measured at $V_{CC}/2$.
- G. t_{PLZ} is measured at V_{OL} + 0.3 V.
- H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC07AIPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	C07AEP	Samples
SN74LVC07AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	C07AMEP	Samples
V62/04654-01XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	C07AEP	Samples
V62/04654-02XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	C07AMEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



PACKAGE OPTION ADDENDUM

6-Feb-2020

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC07A-EP:

Catalog: SN74LVC07A

Automotive: SN74LVC07A-Q1

NOTE: Qualified Version Definitions:

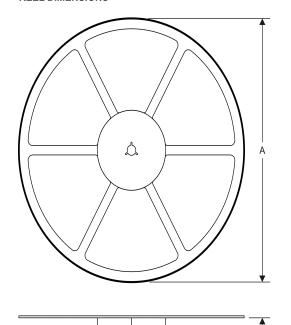
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

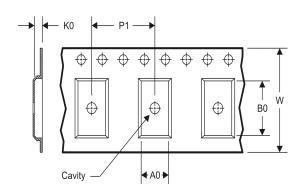
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC07AIPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC07AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC07AIPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LVC07AMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Tl's products are provided subject to Tl's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such Tl products. Tl's provision of these resources does not expand or otherwise alter Tl's applicable warranties or warranty disclaimers for Tl products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated